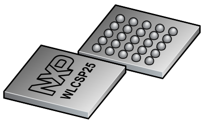
SOT1401-3

WLCSP25, wafer level chip-scale package, 25 bumps, 2.555 mm x 2.525 mm x 0.368 mm body (backside coating included)

10 April 2025 **Package information**



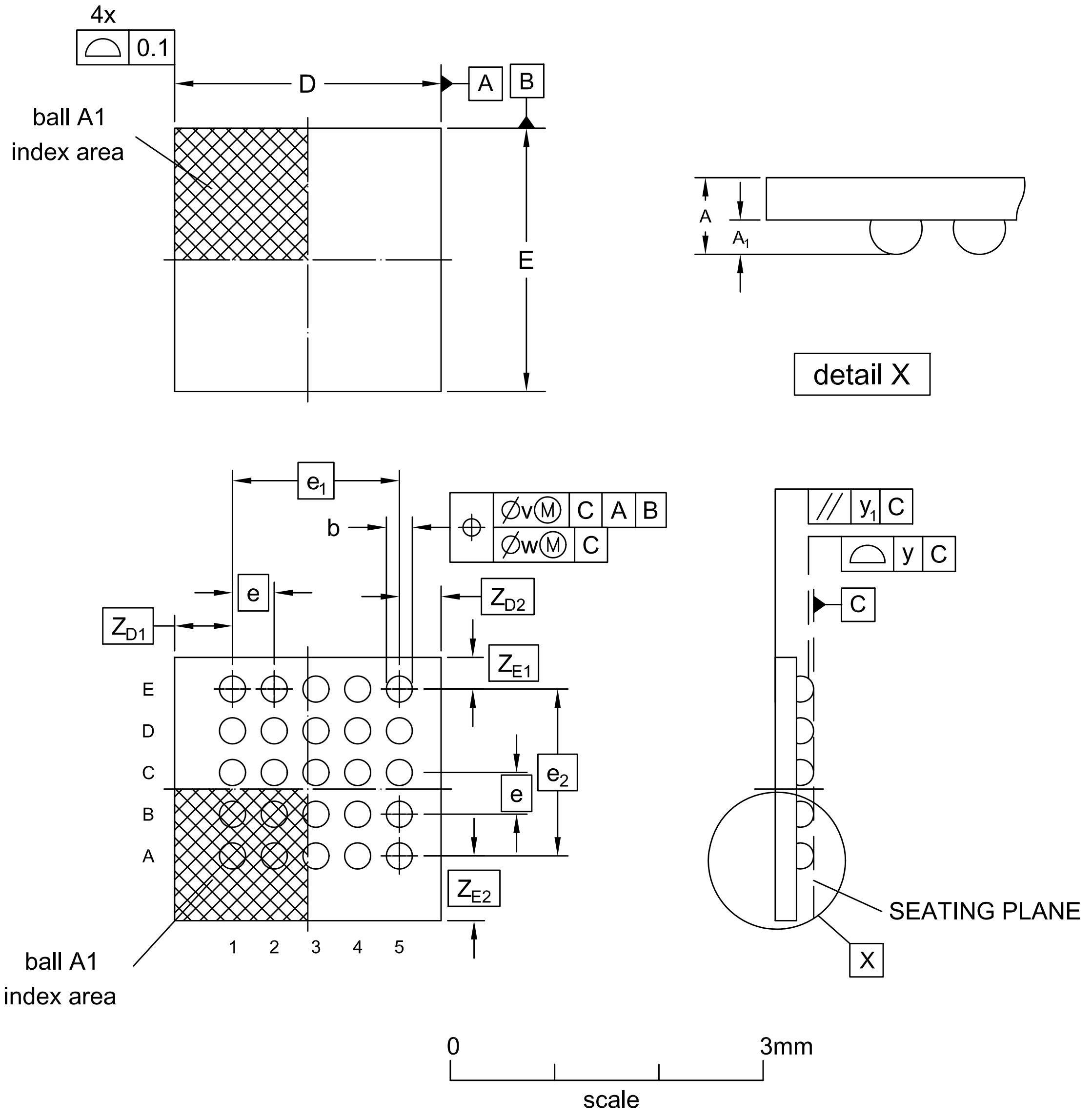
1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP25
Package type industry code	WLCSP25
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	12-05-2017
Manufacturer package code	ASA00848D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.515	2.555	2.595	mm
package width	2.485	2.525	2.565	mm
seated height	0.336	0.368	0.4	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	25	-	

2 Package outline



DIMENSIONS (mm are the original dimensions)

UNIT		A	A_1	b	D	E	e	e_1	e_2	v	w	y	y_1	Z_{D1}	Z_{D2}	Z_{E1}	Z_{E2}
mm	MAX.	0.400	0.195	0.30	2.595	2.565	0.4	1.6	1.6	0.1	0.05	0.05	0.1	0.555	0.304	0.400	0.620
	NOM.	0.368	0.165	0.25	2.555	2.525											
	MIN.	0.336	0.135	0.20	2.515	2.485											

Figure 1. Package outline WLCSP25 (SOT1401-3)

3 Legal information

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